ICVIP 2025

www.icvip.org

Shanghai, China   **December 5-7, 2025**

The 9th International Conference on Video and Image Processing will take place on December 5-7, 2025 in Shanghai, China, which will be sponsored by East China Normal University, China.

The conference features peer-reviewed presentations showcasing the latest technologies, applications and services, keynote talks from renowned academics, special session, and academic visit.

Look forward to meeting you in Shanghai!

Call For Papers

Publication

Accepted papers will be included in International Conference Proceedings, which will be indexed by Ei Compendex, Scopus, IET and CPCI (Web of Science), etc.

*ICVIP2017-2023 Proceedings are included in ACM Digital Library and indexed by Ei Compendex and Scopus already.

Topics

3D images and models
3D imaging
Haptic devices and techniques
High performance image/video indexing algorithms
Human-computer interfaces
Illumination and reflection techniques
Image compression, coding, and encryption
Image data structures for computer graphics
Image feature extraction
Image generation, acquisition, and processing
Color and texture
Compression methods
Computational geometry
Computer animation
Image feature extraction
Image generation, acquisition, and processing
Image geometry and multi-view geometry
Image/video search and browsing on the Web
Image/video summarization and visualization
Image-based modeling and algorithms
Immersive virtual reality
Integration of virtual reality and multimedia
Interactive digital media
Interactive techniques
For more topics please visit: https://icvip.org/cfp.html

Important Dates

Submission Deadline	June 1, 2025
Notification Deadline	June 30, 2025
Registration Deadline	July 15, 2025

Submission Methods

1. Please log in the Easychair Submission System to submit your paper
(*http://confsys.iconf.org/submission/ICVIP2025*)
2. Or send E-mail to icvip2017@outlook.com

Committee

Advisory Chair
Tao Han, Shanghai Jiao Tong University, China

Conference Chairs
Manhua Liu, Shanghai Jiao Tong University, China
Leida LI, Xidian University, China

Program Chairs
Xuefeng Liang, Xidian University, China
Yaohua Deng, Guangdong University of Technology, China
Li Wang, Xidian University, China

Student Program Chair
Hao Yan, Shanghai Jiao Tong University, China
Local Chairs
Yanyan Xu, Shanghai Jiao Tong University, China
Yan Wang, East China Normal University, China

Publicity Chairs
Jianpeng Hu, Shanghai University of Engineering Science, China
Wei Zhang, Nanyang Technological University, Singapore
Ibrahim Mohammed Dweib, Sultan Qaboos University, Sultanate of Oman
Warusia Mohamed Yassin, Universiti Teknikal Malaysia Melaka, Malaysia
Viany Utami Tjhin Bina, Nusantara University, Indonesia

Organized by

华東師范大學
EAST CHINA NORMAL UNIVERSITY

Technically Assisted by

XIDIAN UNIVERSITY   SHANGHAI JIAO TONG UNIVERSITY   SINGAPORE INSTITUTE OF ELECTRONICS

Contact

Conference Secretary: Ms. Lisa Chow

Email icvip2017@outlook.com
Tel: +86-155-7490-6062